

PUBLICATION NUMBER : 59102953
PUBLICATION DATE : 14-06-84

APPLICATION DATE : 03-12-82
APPLICATION NUMBER : 57212997

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INT.CL. : C08L101/00 // C08J 7/04 C08K 3/08 G21F 1/10

TITLE : ELECTRICALLY CONDUCTIVE SYNTHETIC RESIN COMPOSITION

ABSTRACT : PURPOSE: To provide a composition imparted with excellent electrical conductivity and high shielding capability of electromagnetic wave, and suitable as the casing of electronic apparatus, economically without lowering the physical properties and formability, applying metallic film to the surface of small pieces of synthetic resin by electroless plating, and using the pieces as a filler for the composition.

CONSTITUTION: The objective synthetic resin composition contains a filler comprising small pieces of a synthetic resin applied with metallic film (e.g. silver, copper, nickel, cobalt, copper-nickel alloy, nickel-cobalt alloy, nickel-iron alloy, etc.) by electroless plating. The maximum dimension of the piece is preferably 0.01~3mm for particle, 1~3mm for flake, and 0.01~1mm in diameter and 0.5~1mm in length for fiber, and pieces having high aspect ratio are used. The thickness of the metallic film is preferably 1~3microns. The amount of the filler is $\geq 10\%$ based on the base resin, and the resin constituting the piece is selected to have higher heat resistant temperature than the base resin.

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